L Number	Hits	Search Text	DB	Time stamp
-	42	"thinned chip" or "thinned chips"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:56
-	2	5268065.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:49
-	10	"824301"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 15:17
-	3964	"smart card" and chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:14
-	1607	"smart card" with chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:28
-	189	("smart card" with chip$1).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:29
-	13	("4511796" | "4714980" | "4789776" | "4822988" | "4825283" | "5048179" | "5049728" | "5081520" | "5155068" | "5526233" | "5703755" | "5965867" | "5991159").PN.	USPAT	2003/10/24 14:40
-	13	("4511796" | "4714980" | "4789776" | "4822988" | "4825283" | "5048179" | "5049728" | "5081520" | "5155068" | "5526233" | "5703755" | "5965867" | "5991159").PN.	USPAT	2003/10/24 14:48
-	2	5192682.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:50
-	2	6137687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 15:18
-	13	("4511796" | "4714980" | "4789776" | "4822988" | "4825283" | "5048179" | "5049728" | "5081520" | "5155068" | "5526233" | "5703755" | "5965867" | "5991159").PN.	USPAT	2003/10/24 15:23
-	46	4511796.URPN.	USPAT	2003/10/24 15:29
-	225	("chip card" or "chip cards").ti.	USPAT	2003/10/24 16:19
-	1	5122481.pn.	USPAT	2003/11/14 14:18
-	141	lintec.as.	USPAT	2003/11/14 13:32
-	30	lintec.as. and 156/$.ccls.	USPAT	2003/11/14 13:33
-	2996	156/344 or 156/584	USPAT	2003/11/14 13:33
-	109	(156/344 or 156/584) and (dissolv$3 with (adhesive or glue))	USPAT	2003/11/14 13:34

-	42	(156/344 or 156/584) and (dissolv$3 with (adhesive or glue)) and (semiconductor$1 or wafer$1)	USPAT	2003/11/14 13:36
-	8	(156/344 or 156/584) and (dissolv$3 with (adhesive or glue)) and (semiconductor$1 or wafer$1) and dic$3	USPAT	2003/11/14 14:07
-	35	5110388.URPN.	USPAT	2003/11/14 14:03
-	109	(dissolv$3 with (adhesive or glue)) and (semiconductor$1 or wafer$1) and dic$3	USPAT	2003/11/14 14:42
-	7	(dissolv$3 with (adhesive or glue)) and (semiconductor$1 or wafer$1) and dic$3	USOCR	2003/11/14 14:11
-	3	"9948137"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/14 14:21
-	14	(wafer$1 with thinning) with ((dicing or separating) with (chip$1))	USPAT	2003/11/14 14:26
-	7	(wafer$1 with thinning) with ((dicing or separating) with (chip$1))	EPO; JPO; DERWENT; IBM_TDB	2003/11/14 14:26
-	537	438/464	USPAT	2003/11/14 14:43
-	24	438/464 and (dissolv$3 with (adhesive or glue))	USPAT	2003/11/14 14:47
-	5	438/464 and (dissolv$3 with (adhesive or glue))	USOCR	2003/11/14 14:47
-	17646	card with chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:56
-	5109	(card with chip with (circuit$2 or conductive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 17:57
-	11	card with chip with conductive with path	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	0	card with "thinned chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	15	card with thinned with chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:01
-	7	"thinned chip"	USPAT	2003/12/31 18:07
-	17	"thinned chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:11
-	558	(156/$.ccls. or 235/$.ccls.) and (chip$1 with thin$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:12
-	145	(156/$.ccls. or 235/$.ccls.) and (chip$1 near2 thin$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:15

–	62	(156/$.ccls. or 235/$.ccls.) and (chip$1 near2 thin$4) and card$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:22
–	14594	print$3 with coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:23
–	1147	print$3 with coil with (inductive or conductive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:23
–	72	(print$3 near4 (coil near1 (inductive or conductive)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
–	3420	156/344 or 156/584	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
–	394	(156/344 or 156/584) and chip$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:27
–	24	(156/344 or 156/584) and chip$1 and (dissolv$3 with adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:33
–	1487	156/344.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/31 18:34
–	1216	156/344.ccls.	USPAT	2003/12/31 18:37
–	438	156/344.ccls. and (adhesive with (double or two or "2" or second))	USPAT	2003/12/31 18:37
–	2	stromberg with michael	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:52
–	2062	wafer$1 with thin$3 with (divid$3 or separat$3 or dic$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:53
–	1673	wafer$1 with thin$3 with (divid$3 or separat$3 or dic$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:55
–	521	(wafer$1 with thin$3 with (divid$3 or separat$3 or dic$3)).ab.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 22:59
–	28	5268065.URPN.	USPAT	2004/03/18 22:57
–	89	(wafer$1 with thin$3 with (divid$3 or separat$3 or dic$3)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:02
–	89	(wafer$1 with thin$3 with (divid$3 or separat$3 or dic$3)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:15

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–	153	(wafer$1 with (thinned or thinning)).ti.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
–	42	(wafer$1 with (thinned or thinning)).ti. and (dic$3 or divid$3 or separat$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
–	30	(thinned with chip) and ("smart card" or "smart cards")	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:29
–	12	(thinned near3 (chip$1 or die$1)) and ("smart card" or "smart cards")	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:28
–	32	"thinned chip" or "thinned chips"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:30
–	0	(wafer$1 with (thinned or thinning)).ti. and (dic$3 or divid$3 or separat$3) and (smart with card$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:31
–	4	(wafer$1 with (thinned or thinning)).ti. and (smart with card$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:32
–	2	5192682.pn,.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/03/18 23:32
–	9	5192682.URPN.	USPAT	2004/03/18 23:33
–	26	"221470"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 22:42
–	13	"2221470"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 22:42
–	41	5110388.URPN.	USPAT	2004/05/06 22:57
–	15	"4433846"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 09:50
–	40	"smart card" and (thin$4 near2 chip$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 10:07
–	19	card$1 with (thinned with chip$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:03
–	3796	miyamoto and hitachi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:03
–	23	(miyamoto and hitachi) and thinned	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:07

—		6	"6224095"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:05
—		10	"603514"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/07 11:07
—		3	6342434.URPN.	USPAT	2004/05/07 14:53
—		7	("3861978" | "4339297" | "5155068" | "5238876" | "5268065" | "5877034" | "5897337").PN.	USPAT	2004/05/07 14:55
—		45	5155068.URPN.	USPAT	2004/05/07 14:58
—		9	("smart card" or "smart cards") and (lacquer$3 with protect$3)	USPAT	2004/05/10 11:36
—		16	lacquer$3 with protect$3 with chip$1	USPAT	2004/05/10 10:50
—		1	6193163.pn.	USPAT	2004/05/10 11:00
—		37	("4889980" | "4890197" | "4931853" | "4990759" | "4997791" | "5018051" | "5048179" | "5121294" | "5134773" | "5173840" | "5184209" | "5192682" | "5208450" | "5232532" | "5244840" | "5250341" | "5335145" | "5346576" | "5387306" | "5480842" | "5510074" | "5585618" | "5671525" | "5725819" | "5837992" | "5852289" | "5876536" | "5952713" | "5955021" | "5969951" | "5996897" | "6019284" | "6025054" | "6036099" | "6036797" | "6066231" | "6073856").PN.	USPAT	2004/05/10 11:31
—		290	("smart card" or "smart cards") and (chip$1 with surface)	USPAT	2004/05/10 11:36
—		13	("smart card" or "smart cards") and (chip$1 with surface with flush)	USPAT	2004/05/10 11:39
—		5	("smart card" or "smart cards") and (press$3 with chip$1 with surface with flush)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:44
—		35	("smart card" or "smart cards") and (press$3 with chip$1 with surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 13:20
—		2	"9852772"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:56
—		3	"19617621"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 11:57
—		5	provost and solaic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 13:20
—		1	"1981111"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 14:09

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-	3	"1981212"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 14:09
-	2	stromberg and wafer	USPAT	2004/05/10 14:10
-	9	stromberg and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 14:10
-	658	(dissolv$3 with adhesive) and (wafer$1 or semiconductor$1)	USPAT	2004/05/10 14:14
-	298	(dissolv$3 near2 adhesive) and (wafer$1 or semiconductor$1)	USPAT	2004/05/10 14:14
-	110	(dissolv$3 with adhesive) and (wafer$1 or semiconductor$1) and (dic$3)	USPAT	2004/05/10 14:14
-	74	(dissolv$3 with adhesive) and (wafer$1 or semiconductor$1) and (dic$3) and thin$4	USPAT	2004/05/10 14:14
-	6	("4722130" | "5110388" | "5118567" | "5762744" | "5888883" | "6558975").PN.	USPAT	2004/05/10 16:02
-	34	(US-5762744-$ or US-4878991-$ or US-6046073-$ or US-5268065-$ or US-6554193-$ or US-6193163-$ or US-5155068-$ or US-4511796-$ or US-5192682-$ or US-6105873-$ or US-5677524-$ or US-4701600-$ or US-5122481-$ or US-5110388-$ or US-6297076-$ or US-6007920-$ or US-5882956-$ or US-5411921-$ or US-6642127-$ or US-6342434-$ or US-6013534-$ or US-6412701-$ or US-5786988-$ or US-6656819-$ or US-5994205-$).did. or (US-20020134842-$ or US-20020069952-$ or US-20010040186-$).did. or (EP-824301-$ or WO-9948137-$ or WO-9721243-$ or FR-2780534-$).did. or (EP-824301-$ or DE-19601391-$).did.	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03
-	1	(US-3152939-$).did.	USOCR	2004/05/10 16:03
-	0	((US-5762744-$ or US-4878991-$ or US-6046073-$ or US-5268065-$ or US-6554193-$ or US-6193163-$ or US-5155068-$ or US-4511796-$ or US-5192682-$ or US-6105873-$ or US-5677524-$ or US-4701600-$ or US-5122481-$ or US-5110388-$ or US-6297076-$ or US-6007920-$ or US-5882956-$ or US-5411921-$ or US-6642127-$ or US-6342434-$ or US-6013534-$ or US-6412701-$ or US-5786988-$ or US-6656819-$ or US-5994205-$).did. or (US-20020134842-$ or US-20020069952-$ or US-20010040186-$).did. or (EP-824301-$ or WO-9948137-$ or WO-9721243-$ or FR-2780534-$).did. or (EP-824301-$ or DE-19601391-$).did.) and thin44	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03

-	26	((US-5762744-$ or US-4878991-$ or US-6046073-$ or US-5268065-$ or US-6554193-$ or US-6193163-$ or US-5155068-$ or US-4511796-$ or US-5192682-$ or US-6105873-$ or US-5677524-$ or US-4701600-$ or US-5122481-$ or US-5110388-$ or US-6297076-$ or US-6007920-$ or US-5882956-$ or US-5411921-$ or US-6642127-$ or US-6342434-$ or US-6013534-$ or US-6412701-$ or US-5786988-$ or US-6656819-$ or US-5994205-$).did. or (US-20020134842-$ or US-20020069952-$ or US-20010040186-$).did. or (EP-824301-$ or WO-9948137-$ or WO-9721243-$ or FR-2780534-$).did. or (EP-824301-$ or DE-19601391-$).did.) and thin$4	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:03
-	26	((US-5762744-$ or US-4878991-$ or US-6046073-$ or US-5268065-$ or US-6554193-$ or US-6193163-$ or US-5155068-$ or US-4511796-$ or US-5192682-$ or US-6105873-$ or US-5677524-$ or US-4701600-$ or US-5122481-$ or US-5110388-$ or US-6297076-$ or US-6007920-$ or US-5882956-$ or US-5411921-$ or US-6642127-$ or US-6342434-$ or US-6013534-$ or US-6412701-$ or US-5786988-$ or US-6656819-$ or US-5994205-$).did. or (US-20020134842-$ or US-20020069952-$ or US-20010040186-$).did. or (EP-824301-$ or WO-9948137-$ or WO-9721243-$ or FR-2780534-$).did. or (EP-824301-$ or DE-19601391-$).did.) and thin$4	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:20
-	6	("4722130" | "5110388" | "5118567" | "5762744" | "5888883" | "6558975").PN.	USPAT	2004/05/10 16:07
-	11	"475259"	USPAT; US-PGPUB; EPO; DERWENT	2004/05/10 16:26
-	6	("4722130" | "5110388" | "5118567" | "5762744" | "5888883" | "6558975").PN.	USPAT	2004/05/10 16:24
-	0	6656819.URPN.	USPAT	2004/05/10 16:25
-	3	"9925019"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/10 16:27
-	5	"63164336"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 10:25
-	2118	lintec.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:52
-	3	"63148655"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 10:26
-	492	156/344.ccls. and 156/584.ccls.	USPAT	2004/05/11 11:38
-	112	(156/344.ccls. and 156/584.ccls.) and (semiconductor$1 or wafer$1)	USPAT	2004/05/11 11:38

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–	414	lintec.as. and (semiconductor$1 or wafer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:52
–	203	lintec and (semiconductor$1 or wafer$1) and (grind$3 or thin$4 or polish$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 11:53
–	76	lintec and (semiconductor$1 or wafer$1) and (grind$3 or thin$4 or polish$3) and (die or dice)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:03
–	6	("4722130" | "5762744" | "5989982" | "6054372" | "6083811" | "6297131").PN.	USPAT	2004/05/11 12:00
–	1148	GIESECKE and DEVRIENT	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:03
–	22	(GIESECKE and DEVRIENT) and semiconductor$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:05
–	31	(GIESECKE and DEVRIENT) and (semiconductor$1 or wafer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
–	10	"624341"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:12
–	5	"5912185"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:13
–	7	"981156"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:14
–	3	"6465330"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 12:14
–	5	("4756968" | "5714029" | "5888883" | "6126772" | "6312800").PN.	USPAT	2004/05/11 12:15
–	33	4756968.URPN.	USPAT	2004/05/11 12:16
–	1	6083811.pn.	USPAT	2004/05/11 12:38
–	48	"dicing film" with adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:37
–	5	"10231602"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:41

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-	23789	((wafer$1 or semiconductor$1) with (grind$3 or thin$4)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:42
-	946	((wafer$1 or semiconductor$1) with (grind$3 or thin$4)).ti.	USPAT	2004/05/11 14:42
-	93	((wafer$1 or semiconductor$1) with (grinding or thinning or thinned)).ti.	USPAT	2004/05/11 15:02
-	10306	"19921230"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:03
-	1	"19921230" and haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
-	591	haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
-	86	(GIESECKE and DEVRIENT) and haghiri	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
-	6	(GIESECKE and DEVRIENT) and haghiri and (semiconductor$1 or wafer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:05
-	10311	"19921230"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 20:49
-	1	"19921230".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 20:49
-	6	"19811115"	USPAT	2004/08/11 21:07
-	1521	"19811115"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:07
-	2	"19811115".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:07
-	0	"19812120"	USPAT	2004/08/11 21:32
-	0	"19812120".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:32
-	0	"19812120".pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:33

–	3542	156/584 or 156/344	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:39
–	573	(156/584 or 156/344) and (semiconductor$1 or wafer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:41
–	322	(156/584 or 156/344).ccls. and (semiconductor$1 or wafer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/11 21:41
–	56	card$1.ti. and (chip$1 with (exterior or external$2) with surface)	USPAT	2004/08/20 20:50
–	20	card$1.ti. and (chip$1 with (exterior or external$2) with surface with (circuit$2 or coil))	USPAT	2004/08/20 20:50
–	10	"824301"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/20 20:16
–	48	card$1.ti. and (chip$1 with (exterior or external$2) with surface) and (circuit$2 or coil)	USPAT	2004/08/20 20:57
–	28	(card$1.ti. and (chip$1 with (exterior or external$2) with surface) and (circuit$2 or coil)) not (card$1.ti. and (chip$1 with (exterior or external$2) with surface with (circuit$2 or coil)))	USPAT	2004/08/20 20:50
–	24	card$1.ti. and (chip$1 with (exterior or external$2) with surface) and ((circuit$2 or coil) with print$3)	USPAT	2004/08/20 20:57
–	4	"6412701" AND PRINT$3	USPAT	2004/08/22 22:14